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# ***Laser-based Micro- and Nanoprocessing X***

**Udo Klotzbach  
Kunihiko Washio  
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*Editors*

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# Contents

vii *Authors*  
ix *Conference Committee*

---

## **SESSION 1 LASER MICRO-STRUCTURING AND PROCESSING I**

---

- 9736 02 **Laser assisted micro-welding of ultra-thin glass wafers (Invited Paper)** [9736-1]  
9736 04 **Trends in laser micromachining** [9736-3]

---

## **SESSION 2 LASER NANO-STRUCTURING AND PROCESSING**

---

- 9736 08 **Femtosecond pulsed light polarization induced effects in direct laser writing 3D nanolithography (Invited Paper)** [9736-6]  
9736 09 **Rapid fabrication of microdevices using laser direct writing and replica moulding technique** [9736-7]  
9736 0B **Ultrafast graphene and carbon nanotube film patterning by picosecond laser pulses** [9736-9]

---

## **SESSION 3 LASER MICRO-STRUCTURING AND PROCESSING II**

---

- 9736 0C **microPREP: a new laser tool for high-volume sample preparation (Invited Paper)** [9736-10]  
9736 0D **Formation of copper micropatterns by laser direct writing using copper nanoparticle ink** [9736-11]  
9736 0E **Multiwave hybrid laser processing of micrometer scale features for flexible electronic applications** [9736-12]  
9736 0F **Zero degree contour cutting below 100  $\mu\text{m}$  feature size with femtosecond laser** [9736-14]

---

## **SESSION 4 DIRECT WRITE PROCESSING, ABLATION, AND SURFACE MODIFICATION I**

---

- 9736 0G **Nanotextured surfaces for surface enhanced Raman spectroscopy and sensors (Invited Paper)** [9736-15]  
9736 0K **Nanosecond pulsed laser generation of holographic structures on metals** [9736-19]

<b>SESSION 5</b>	<b>HIGH SPEED LASER BEAM ENGINEERING SYSTEMS FOR HIGH POWER ULTRA SHORT PULSED LASER I</b>
9736 0L	<b>Electro-optic and acousto-optic laser beam scanners (Invited Paper) [9736-20]</b>
9736 0N	<b>Ultra high-speed micromachining of transparent materials using high PRF ultrafast lasers and new resonant scanning systems [9736-22]</b>
9736 0O	<b>Throughput optimization for laser micro structuring [9736-23]</b>
9736 0P	<b>Enhancing ablation efficiency in micro structuring using a deformable mirror for beam shaping of ultra-short laser pulses [9736-24]</b>
<b>SESSION 6</b>	<b>HIGH SPEED LASER BEAM ENGINEERING SYSTEMS FOR HIGH POWER ULTRA SHORT PULSED LASER II</b>
9736 0R	<b>High-throughput machining using high average power ultrashort pulse lasers and ultrafast polygon scanner (Invited Paper) [9736-26]</b>
9736 0S	<b>Micro drilling using deformable mirror for beam shaping of ultra-short laser pulses [9736-27]</b>
<b>SESSION 7</b>	<b>DIRECT WRITE PROCESSING, ABLATION, AND SURFACE MODIFICATION II: ULTRAFAST LASER MACHINING APPLICATIONS</b>
9736 0T	<b>Simultaneous spatial and temporal focusing: a route towards confined nonlinear materials processing (Invited Paper) [9736-28]</b>
9736 0U	<b>Eternal 5D data storage by ultrafast laser writing in glass (Invited Paper) [9736-29]</b>
9736 0V	<b>Surface treatment with small laser spots: an approach for the comparison of process parameters [9736-30]</b>
9736 0W	<b>Exploring polygon scanner head capabilities for ultra-short pulse laser texturing [9736-31]</b>
<b>SESSION 8</b>	<b>LARGE AREA MICRO/NANO STRUCTURING, LASER INTERFERENCE PATTERNING</b>
9736 0Y	<b>Improve large area uniformity and production capacity of laser interference lithography with beam flattening device [9736-33]</b>
9736 0Z	<b>World record in high speed laser surface microstructuring of polymer and steel using direct laser interference patterning [9736-34]</b>
9736 11	<b>Direct laser interference patterning for decreased bacterial attachment [9736-36]</b>
9736 12	<b>Directionality in laser fabrication of 3D graphitic microwires in diamond [9736-37]</b>

---

**SESSION 9    ULTRAFAST LASER MACHINING APPLICATIONS I**

---

- 9736 14    **CFRP bonding pre-treatment with laser radiation of 3 $\mu$ m wavelength: laser/material interaction** [9736-39]
- 9736 15    **Picosecond laser welding of optical to metal components** [9736-40]

---

**SESSION 10    ULTRAFAST LASER MACHINING APPLICATIONS I**

---

- 9736 17    **Photochemical reduction of graphene oxide (GO) by femtosecond laser irradiation** [9736-42]
- 9736 19    **Analysis of process parameter for the ablation of optical glasses with femto- and picosecond laser pulses** [9736-44]

---

**SESSION 11    ADVANCED LASER STRUCTURING FOR ENERGY STORAGE AND CONVERSION**

---

- 9736 1D    **Flexible carbon micro-supercapacitors prepared by direct cw-laser writing** [9736-48]

---

**POSTER SESSION**

---

- 9736 1G    **System design of programmable 4f phase modulation techniques for rapid intensity shaping: a conceptual comparison** [9736-51]
- 9736 1I    **Heat transfer analysis of two wavelengths laser microprocessing inside glass** [9736-53]
- 9736 1J    **Online process monitoring at quasi-simultaneous laser transmission welding using a 3D-scanner with integrated pyrometer** [9736-54]
- 9736 1K    **Pattern transfer, self-organized surface nanostructuring, and nanodrilling of sapphire using nanosecond laser irradiation** [9736-55]
- 9736 1M    **Surface separation investigation of ultrafast pulsed laser welding** [9736-57]
- 9736 1O    **Picosecond pulsed laser processing of polycrystalline diamond and cubic boron nitride composite materials** [9736-59]
- 9736 1P    **Advances in 193 nm excimer lasers for mass spectrometry applications** [9736-60]
- 9736 1S    **Optical emission enhancement in laser-induced breakdown spectroscopy using micro-torches** [9736-63]
- 9736 1T    **The influence of ArF excimer laser micromachining on physicochemical properties of bioresorbable poly(L-lactide)** [9736-64]



# Authors

Numbers in the index correspond to the last two digits of the six-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first four digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Abramski, Krzysztof M., 09, 1T  
Ackermann, Roland, 0T  
Antończak, Arkadiusz J., 09, 1T  
Ardron, Marcus, 0K  
Balčytis, Armandas, 0G  
Bayer, L., 1K  
Bechtold, Peter, 0L  
Beresna, M., 0U  
Bergner, Klaus, 0T  
Blass, David, 14  
Bliedtner, Jens, 19  
Bobrinetskiy, Ivan I., 0B  
Bonati, Guido, 1P  
Booth, M. J., 12  
Burgui, Saioa, 11  
Cai, Jinguang, 0D, 1D  
Carter, Richard M., 15, 1M  
Čerkauskaitė, A., 0U  
Chen, Jinanyong, 15, 1M  
Chen, K., 1S  
Delmdahl, Ralph, 1P  
Dickmann, Klaus, 0P, 0S  
Dilger, Klaus, 0V, 14  
Dostalek, M., 1J  
Drevinskas, R., 0U  
Ehrhardt, M., 1K  
Elder, Ian, 15  
Emelianov, Alexey V., 0B  
Enoki, Shinichi, 1I  
Esser, Hans-Gerd, 1P  
Esser, M. J. Daniel, 15  
Fan, Lidan, 0D  
Faucon, M., 0W  
Fleureau, M., 0W  
Friedel, Susanna, 0F  
Friedrich, Maria, 19  
Fu, Chien-Chung, 0Y  
Gaebler, Frank, 04  
Gailevičius, Darius, 08  
Gamaly, Eugene, 08  
Gil, Carmen, 11  
Grefe, Hinrich, 0V  
Guenther, Denise, 11  
Gurevich, E. L., 0O  
Hand, Duncan P., 0K, 15, 1M  
Harth, F., 0N  
Heber, Jörg, 1G  
Heberle, Johannes, 0L  
Helbig, Ralf, 11  
Held, Andrew, 04  
Herrmann, T., 0N  
Hevonkorpi, V., 02  
Hierl, S., 1J  
Hillman, J., 0E  
Höche, Thomas, 0C  
Hoffman, Hans-Dieter, 14  
Hoppius, Jan S., 0O  
Huang, X., 1S  
Janschek, Klaus, 1G  
Jonavičius, Tomas, 08  
Jungbluth, Bernd, 14  
Juodkazis, Saulius, 08, 0G  
Juodkazytė, Jurga, 0G  
Kammel, Robert, 0T  
Kanitz, A., 0O  
Kazansky, P. G., 0U  
Kling, R., 0W  
Kloetzer, Sascha, 0R  
Krause, Michael, 0C  
Kreling, Stefan, 0V, 14  
Lamb, Robert A., 15  
Lang, Valentin, 0Z  
Lasa, Inigo, 11  
Lasagni, Andrés F., 0Z, 11  
L'huillier, J. A., 0N  
Li, S., 1S  
Li, Xijun, 0G  
Lin, Te-Hsun, 0Y  
Liu, L., 1S  
Loeschner, Udo, 0R  
Lorenz, P., 1K  
Lu, Y. F., 1S  
Lu, Yao, 1S  
Lundén, H., 02  
Määttänen, A., 02  
Malinauskas, Mangirdas, 08  
Matsumoto, Aoi, 1I  
Meier, Linus, 1O  
Miller, D., 0E  
Mincuzzi, G., 0W  
Mizeikis, Vygantas, 08  
Muttaqin, 17  
Nakamura, Takahiro, 17  
Niaura, Gediminas, 0G  
Nolte, Stefan, 0T  
Nyga, Sebastian, 14  
Ohmura, Etsuji, 1I  
Oropeza, M., 0E

Ostendorf, A., 00  
Otero, Nerea, 0B  
Patel, A., 0U  
Petsch, Tino, 0C  
Pezowicz, Celina, 1T  
Pfaff, Josquin, 1O  
Piontek, M. C., 0N  
Qin, Gang, 0D  
Rekštytė, Sima, 08  
Risser, C., 0E  
Roch, Teja, 0Z  
Romero, Pablo M., 0B  
Roth, Matthias, 1G  
Salter, P. S., 12  
Sato, Shunichi, 17  
Schille, Joerg, 0R  
Schindler, Christian, 19  
Schmälzl, A., 1J  
Schmidt, Michael, 0L  
Schneider, Lutz, 0R  
Seniutinas, Gediminas, 0G  
Skupin, Stefan, 0T  
Smarra, Marco, 0P, 0S  
Solano, Cristina, 11  
Steger, S., 1J  
Stępak, Bogusz D., 09, 1T  
Stolberg, Klaus, 0F  
Strauß, Johannes, 0L  
Streek, André, 0R  
Strube, Anja, 0S  
Sukhman, Y., 0E  
Sun, B., 12  
Szustakiewicz, Konrad, 1T  
Tamaki, Takayuki, 1I  
Thomas, Jens U., 0T  
Thomson, Robert R., 15, 1M  
Toledo-Arana, Alejandro, 11  
Troughton, Michael, 15  
Valle, Jaoiné, 11  
van Nunen, Joris, 04  
Wagner, Uwe, 0C  
Walter, Christian, 1O  
Warhanek, Maximilian G., 1O  
Watanabe, Akira, 0D, 1D  
Wegener, Konrad, 1O  
Werner, Carsten, 11  
Weston, Nick J., 0K  
Westphalen, Thomas, 14  
Włodarczyk, Krystian L., 0K  
Wu, Yu-Xiang, 0Y  
Yahata, Keisuke, 1I  
Yang, Yin-Kuang, 0Y  
Yu, Chun-Wen, 0Y  
Zajadacz, J., 1K  
Zhang, J., 0U  
Zimmer, K., 1K



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**Haibin Zhang**, Electro Scientific Industries, Inc. (United States)
- 3 Laser Micro-Structuring and Processing II  
**François Courvoisier**, FEMTO-ST (France)
- 4 Direct Write Processing, Ablation, and Surface Modification I  
**Kunihiko Washio**, Paradigm Laser Research Ltd. (Japan)
- 5 High Speed Laser Beam Engineering Systems for High Power Ultra Short Pulsed Laser I  
**Michael J. Withford**, Macquarie University (Australia)
- 6 High Speed Laser Beam Engineering Systems for High Power Ultra Short Pulsed Laser II  
**Andrés F. Lasagni**, Fraunhofer IWS Dresden (Germany)
- 7 Direct Write Processing, Ablation, and Surface Modification II: Ultrafast Laser Machining Applications  
**Hong-Bo Sun**, Jilin University (China)
- 8 Large Area Micro/Nano Structuring, Laser Interference Patterning  
**Chunlei Guo**, University of Rochester (United States)
- 9 Ultrafast Laser Machining Applications I  
**Wilhelm Pfleging**, Karlsruhe Institute of Technology (Germany)

- 10 Ultrafast Laser Machining Applications II  
**Craig B. Arnold**, Princeton University (United States)
- 11 Advanced Laser Structuring for Energy Storage and Conversion  
**Udo Klotzbach**, Fraunhofer IWS Dresden (Germany)

